

CLAIMS

What is claimed is:

1. A terminal pin comprising:
an elongated pin for insertion into a hole of a printed circuit board; and
5 a flange having a shoulder to abut the printed circuit board into which the pin is inserted, the flange being chamfered to provide a vent to the hole of the printed circuit board.
2. A terminal pin as claimed in claim 1 comprising two opposed chamfers.
3. A terminal pin as claimed in claim 2 wherein edges of the two opposed chamfers
10 are at about the periphery of the pin.
4. A circuit module comprising:
a circuit substrate having circuitry thereon; and
at least one rigid terminal pin attached to the circuit substrate, the
terminal pin including a flange having a shoulder to abut a printed circuit board
15 into which the pin is inserted, the flange being chamfered to provide a vent to a hole of the printed circuit board into which the pin is inserted.
5. A module as claimed in claim 4 comprising two opposed chamfers.
6. A module as claimed in claim 5 wherein edges of the two opposed chamfers are at about the periphery of the pin.
- 20 7. A module as claimed in claim 4 wherein the pin is electrically connected to the circuitry.

8. A circuit board assembly comprising:
a printed circuit board;
a circuit module having circuitry thereon; and
at least one rigid terminal pin attached to the circuit module, the terminal
5 pin including a flange having a shoulder to abut the printed circuit board, the
flange being chamfered to provide a vent to a hole of the printed circuit board
into which the pin is inserted.
9. A circuit board assembly as claimed in claim 8 comprising two opposed
chamfers.
- 10 10. A circuit board assembly as claimed in claim 9 wherein edges of the two
opposed chamfers are at about the periphery of the pin.
11. A circuit board assembly as claimed in claim 8 wherein the pin is electrically
connected to the circuitry.
- 15 12. A method of soldering a circuit module to a printed circuit board comprising:
providing at least one rigid terminal pin on the circuit module, the
terminal pin including a flange having a shoulder to abut a hole in a printed
circuit board into which the pin is inserted, the flange having a chamfer facing
the printed circuit board;
20 positioning the module on the printed circuit board with the pin inserted
into a hole in the printed circuit board and the flange shoulder abutting the
printed circuit board, the chamfer providing a vent to the hole; and
causing solder to flow through an opening between the chamfer and
printed circuit board.
- 25 13. A method as claimed in claim 12 wherein the solder is applied in a wave
soldering process.

14. A method as claimed in claim 12 wherein the solder is applied in a reflow soldering process.
15. A method as claimed in claim 12 comprising two opposed chamfers.
16. A method as claimed in claim 15 wherein edges of the two opposed chamfers
5 are at about the periphery of the pin.